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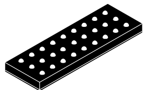
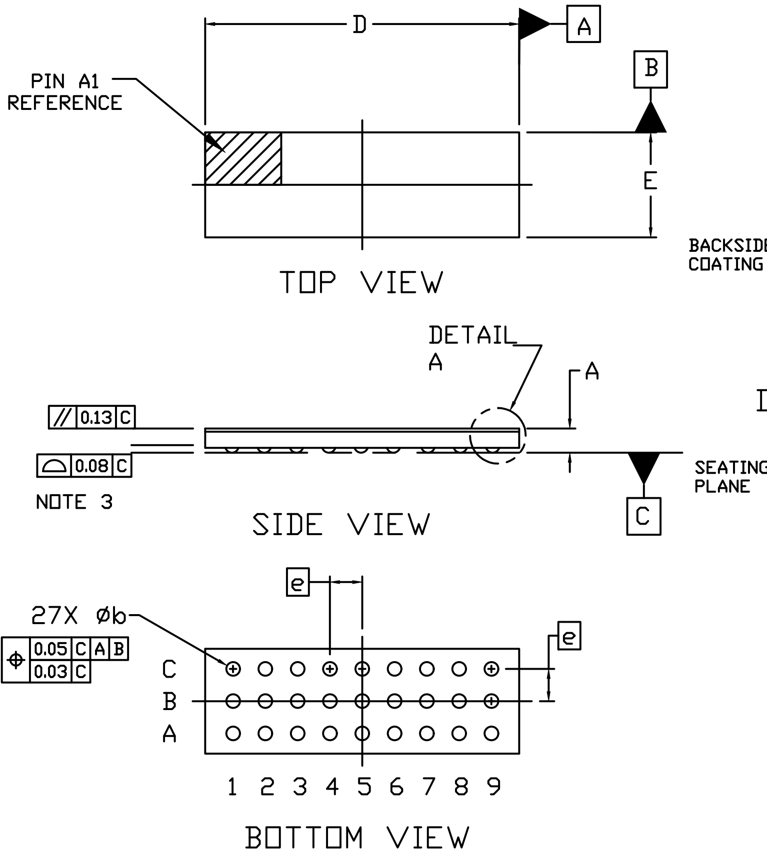


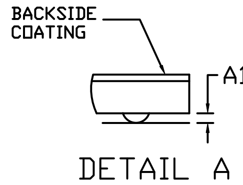
SCALE 4:1

WLCSP27, 3.89x1.30, 0.4P
CASE 567NJ
ISSUE A

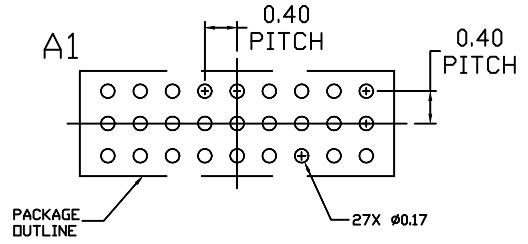
DATE 22 SEP 2020



NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2009.
2. CONTROLLING DIMENSION: MILLIMETERS
3. COPLANARITY APPLIES TO THE SPHERICAL CROWNS OF THE SOLDER BALLS.



DIM	MILLIMETERS MIN.	NOM.	MAX.
A	---	---	0.33
A1	0.04 REF		
b	0.12	0.17	0.22
D	3.84	3.89	3.94
E	1.25	1.30	1.35
e	0.40 BSC		



RECOMMENDED
MOUNTING FOOTPRINT

* For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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